

REMARKS

The Applicants appreciate the thoroughness with which the subject application has been examined. By this amendment certain claims have been amended as set forth above to overcome the Examiner's rejections and more concisely claim and describe the present invention. Claims 1-6, 8-16 and 26 remain in the application for reconsideration by the Examiner. The Examiner's allowance of all pending claims is earnestly solicited.

Claim 13 has been rejected under Section 112, second paragraph as indefinite for failing to particularly point out and distinctly claim what the Applicants regard as the invention.

Claim 13 has been amended as indicated above to overcome the rejection under Section 112.

Claims 1-5, 7-10, 12-16 and 26 have been rejected under Section 102(b) as anticipated by Kloen (6,229,221). Claims 6 and 11 have been rejected under Section 103(a) over Kloen in view of the Applicant's admitted prior art.

To further define the invention over the art of record the last paragraph of claim 1 has been revised to claim "a second interconnect structure connecting one of the plurality of contact pads to a plurality of first interconnect structures, wherein a portion of the second interconnect structure is disposed in the bond pad level and connected to each one of the plurality of first interconnect structures through a conductive via."

Support for this amendment is found in Figures 11 and 13 and specification text paragraphs [0040] – [0044]. As the Applicants explain in paragraph [0027], by forming interconnect structures in the bond pad level ("wherein a portion of the interconnect structure configured to transfer power is disposed in the bond pad level") according to the teachings of the present invention, one metallization layer and the corresponding masks steps are eliminated.

Kloen discloses an interconnect structure as illustrated in Figure 2, comprising a circuit connecting region 22 of the bond pad 3 further connected to the second patterned metal layer 19 through a connecting area 21. Kloen suggests that this configuration is advantageous because the circuit connecting region of the bond pad is substantially outside of the wire

bonding region, and the layer of passivating material is substantially free of interruptions beneath the wire bonding region.

But Kloen fails to disclose or suggest “a second interconnect structure connecting one of the plurality of contact pads to a plurality of first interconnect structures, wherein a portion of the first interconnect structure is disposed in the bond pad level and connected to each one of the plurality of the first interconnect structures through a conductive via,” as claimed by the Applicants.

Retained rejected claims 2-6, 8-11 and 26 depend directly or indirectly from amended claim 1. Certain of these claims have been amended to comport with the amendments to claim 1 from which they depend as indicated above. The Applicants respectfully submit that these claims are allowable as they each include one or more elements that further distinguish the art of record.

Claim 7 has been cancelled, with the Applicants reserving the right to prosecute this claim or a similar claim in a continuing application. Cancellation of claim 7 is not to be construed as an admission as to the validity of the rejection or the applicability of the cited art.

Claim 12 has been amended as set forth above to more clearly and concisely distinguish the Kloen reference. The last paragraph of amended claim 12 now claims, “a second interconnect structure coplanar with at least one of the plurality of contact pads and electrically connected thereto, the second interconnect structure comprising a plurality of conductive elements each connected to one of the first interconnect structures through a conductive via.”

As discussed above, Kloen does not disclose or suggest at least the second interconnect structure as claimed by the Applicants in amended claim 12.

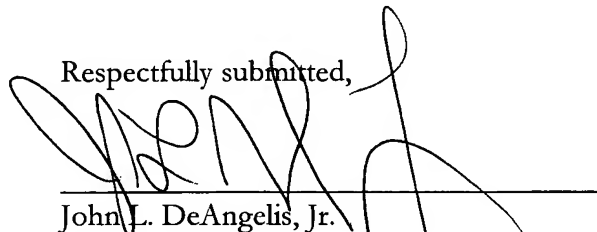
Rejected claims 13-16 depend directly or indirectly from independent amended claim 12. The Applicants respectfully submit that these claims are allowable as each includes one or more elements that further distinguish the art of record.

The Applicants have attempted to comply with all of the points raised in the Office Action and it is believed that the remaining claims in the application are now in condition for allowance. In view of the foregoing amendments and discussion, it is requested that the Examiner's rejections have been overcome. It is respectfully requested that the Examiner

reconsider these rejections and issue a Notice of Allowance for all the claims pending in the application.

If a telephone conference will assist in clarifying or expediting this Amendment or the claim changes made herein, the Examiner is invited to contact the undersigned at the telephone number below.

Respectfully submitted,



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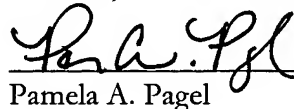
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CERTIFICATE OF MAILING

I HEREBY CERTIFY that the foregoing Amendment is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 1st day of May 2006.



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